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[54] **RESIST PROCESSING APPARATUS FOR A RECTANGULAR SUBSTRATE**

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[58] **Field of Search** 118/52, 56, 66, 118/319, 321, 323; 134/902, 144

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[57] **ABSTRACT**

A apparatus of resist-processing a rectangular substrate including a resist coating step of supplying resist solution to the substrate, while rotating it, to form resist film at least on one surface of it and a resist removing step of jetting removing liquid, which can solve resist, to both surfaces of it at its side peripheral portions to remove the resist film from them.

7 Claims, 19 Drawing Sheets